

Clock Generator Selector Guide

Universal clock generators simplify traditional board designs by synthesizing frequencies from either a reference input clock or a common low-cost crystal, providing low-jitter output clocks. When used together with Microsemi clock distribution fanout buffers, the clock generators provide customers with improved board performance and complete timing solutions.

Any-Rate Clock Synthesis Devices

Product	Independent Output Freq. Families	Inputs	Crystal Input Freq. Range	Xtal Oscillator or CMOS Input Freq. Range	Diff Input Freq. Range	Low-Jitter APLLs	Typical Jitter fs RMS	NCO Mode	NCO ppb	Diff Outputs	CMOS Outputs	Output Freq. Range	NV Memory	Host Bus	Supply Voltage	Pkg Size, mm
MAX24405	2	1 XTAL/SE, 3 D/SE	25 M–52 M	9.72 M–160 M	9.72 M–750 M	2	180 ¹			0–5	0–10	<1 Hz–750 M	Ext EE	SPI	3.3 + 1.8	10 × 10
MAX24505	2	1 XTAL/SE, 3 D/SE	25 M–52 M	9.72 M–160 M	9.72 M–750 M	2	180 ¹			0–5	0–10	<1 Hz–750 M	Int EE	SPI	3.3 + 1.8	10 × 10
MAX24410	2	1 XTAL/SE, 3 D/SE	25 M–52 M	9.72 M–160 M	9.72 M–750 M	2	180 ¹			0–10	0–20	<1 Hz–750 M	Ext EE	SPI	3.3 + 1.8	10 × 10
MAX24510	2	1 XTAL/SE, 3 D/SE	25 M–52 M	9.72 M–160 M	9.72 M–750 M	2	180 ¹			0–10	0–20	<1 Hz–750 M	Int EE	SPI	3.3 + 1.8	10 × 10
ZL30250	1	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M–1250 M	1	160 ¹	•	0.01	0–3	0–6	<1 Hz–1035 M ²	Ext EE ³	SPI/I2C	3.3 + 1.8	5 × 5
ZL30251	1	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M–1250 M	1	160 ¹	•	0.01	0–3	0–6	<1 Hz–1035 M ²	Int EE ³	SPI/I2C	3.3 + 1.8	5 × 5
ZL30244	2	2 XTAL/SE, 6 D/SE	25 M–60 M	9.72 M–300 M	9.72 M–1250 M	2	160 ¹	•	0.01	0–6	0–12	<1 Hz–1035 M ²	Ext EE ³	SPI/I2C	3.3 + 1.8	5 × 10
ZL30245	2	2 XTAL/SE, 6 D/SE	25 M–60 M	9.72 M–300 M	9.72 M–1250 M	2	160 ¹	•	0.01	0–6	0–12	<1 Hz–1035 M ²	Int EE ³	SPI/I2C	3.3 + 1.8	5 × 10
ZL30260	2	1 XTAL/SE, 3D/SE	25 M–60 M	9.72 M–300 M	9.72 M–1250 M	1	170 ¹	•	0.01	0–6	0–12	1 Hz–1035 M ²	Ext EE ⁴	SPI/I2C	Note ⁵	8 × 8
ZL30261	2	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M–1250 M	1	170 ¹	•	0.01	0–6	0–12	1 Hz–1035 M ²	Int EE ⁴	SPI/I2C	Note ⁵	8 × 8
ZL30262	2	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M–1250 M	1	170 ¹	•	0.01	0–10	0–20	1 Hz–1035 M ²	Ext EE ⁴	SPI/I2C	Note ⁵	8 × 8
ZL30263	2	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M–1250 M	1	170 ¹	•	0.01	0–10	0–20	1 Hz–1035 M ²	Int EE ⁴	SPI/I2C	Note ⁵	8 × 8
ZL30264	4	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M–1250 M	2	170 ¹	•	0.01	0–6	0–12	1 Hz–1035 M ²	Ext EE ⁴	SPI/I2C	Note ⁵	8 × 8
ZL30265	4	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M–1250 M	2	170 ¹	•	0.01	0–6	0–12	1 Hz–1035 M ²	Int EE ⁴	SPI/I2C	Note ⁵	8 × 8
ZL30266	4	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M–1250 M	2	170 ¹	•	0.01	0–10	0–20	1 Hz–1035 M ²	Ext EE ⁴	SPI/I2C	Note ⁵	8 × 8
ZL30267	4	1 XTAL/SE, 3 D/SE	25 M–60 M	9.72 M–300 M	9.72 M–1250 M	2	170 ¹	•	0.01	0–10	0–20	1 Hz–1035 M ²	Int EE ⁴	SPI/I2C	Note ⁵	8 × 8

Gen 1-4 PCIe Clock Generators

Product	Independent Output Freq. Families	Inputs	Crystal Input Freq. Range	Xtal Oscillator or CMOS Input Freq. Range	Low-Jitter APLLs	Typical Jitter fs RMS	Default Output Configurartions	Output Freq. Range	Host Bus	Supply Voltage	Pkg Size, mm
ZL30281	1	1 XTAL	25M	25 M	1	160	4	25 M, 100 M	SPI/I2C	3.3 + 1.8	5 × 5
ZL30282	2	1 XTAL	50 M	50 M	1	160	8	25 M, 75 M, 100 M	SPI/I2C	Note ⁵	8 × 8

Abbreviation Key: D = differential
Int EE = internal EEPROM
3 = up to four configurations (pin-selectable)

SE = single-ended (CMOS)
OTP = one-time programmable
4 = up to eight configurations (pin-selectable)

NCO = numerically controlled oscillator
1 = integer-mode APLL-only operation
5 = 2.5 V only, 3.3 V only, 1.8 V + 2.5 V, 1.8 V + 3.3 V

Ext EE = external EEPROM
2 = spread spectrum-capable

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Rate Conversion/Jitter Attenuation Devices

Product	Independent Output Freq. Families	Inputs	Crystal Input Freq. Range	Xtal Oscillator or CMOS Input Freq. Range	Diff Input Freq. Range	Low-Jitter APLLs	Typical Jitter fs RMS	DPLL Features: Ref. Switching/ Holdover/ DPLL Bandwidth	NCO Mode	NCO ppb	Diff Outputs	CMOS Outputs	Output Freq. Range	NV Memory	Host Bus	Supply Voltage	Pkg Size, mm
MAX24605	2	1 XTAL/SE, 3 D/SE	25 M–52 M	2 kHz–160 M	2 kHz–750 M	2	180'	Glitchless/ Digital Hold/ 4 Hz–400 Hz	•	<0.001	0–5	0–10	<1 Hz–750 M	Ext EE	SPI	3.3 + 1.8	10 × 10
MAX24610	2	1 XTAL/SE, 3 D/SE	25 M–52 M	2 kHz–160 M	2 kHz–750 M	2	180'	Glitchless/ Digital Hold/ 4 Hz–400 Hz	•	<0.001	0–10	0–20	<1 Hz–750 M	Ext EE	SPI	3.3 + 1.8	10 × 10
ZL30159	1	1 XTAL, 1 D	20 M or 24.578 M	1 Hz–177.5 M	1 Hz–750 M	1	<1000				0	2	1 Hz–177.5 M		SPI/I2C	3.3 + 1.8	9 × 9
ZL30252	1	1 XTAL/SE, 3 D/SE	25 M–60 M	1 kHz–300 M	1 kHz–1250 M	1	160'	Glitchless/ Digital Hold/ 14 Hz–500 Hz	•	0.01	0–3	0–6	<1 Hz–1035 M ²	Ext EE ³	SPI/I2C	3.3 + 1.8	5 × 5
ZL30253	1	1 XTAL/SE, 3 D/SE	25 M–60 M	1 kHz–300 M	1 kHz–1250 M	1	160'	Glitchless/ Digital Hold/ 14 Hz–500 Hz	•	0.01	0–3	0–6	<1 Hz–1035 M ²	Int EE ³	SPI/I2C	3.3 + 1.8	5 × 5
ZL30254	1	1 XTAL, 2 SE	49.152 MHz	8 kHz or 25 MHz		1	<1 ps	Glitchless/ Digital Hold/ 25 Hz			2	0	125 MHz or 156.25 MHz		None	3.3 + 1.8	5 × 5
ZL30255	2	2 XTAL/SE, 6 D/SE	25 M–60 M	1 kHz–300 M	1 kHz–1250 M	2	160'	Glitchless/ Digital Hold/ 14 Hz–500 Hz	•	0.01	0–6	0–12	<1 Hz–1035 M ²	Int EE ³	SPI/I2C	3.3 + 1.8	5 × 10
ZL30256	3	5 D/10 SE	25 M–52 M	9.72 MHz–156.25 MHz	1 kHz–1045 M	3	190	Glitchless/Digital Hold 14 Hz–470 Hz	•	~0.0000035	0–8	0–16 +2	1 Hz–1045 M	Int EE ⁴	SPI/I2C	3.3 + 1.8	11 × 11

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SE = single-ended (CMOS)
Int EE = internal EEPROM
2 = spread spectrum-capable

NCO = numerically controlled oscillator
OTP = one-time programmable
3 = up to four configurations pin-selectable
4 = up to three configurations pin-selectable



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